

ABSTRACT

An object of the present invention is to provide an epoxy resin composition which can be used as a semiconductor encapsulating resin and in which the improvement of flame retardancy can be attained by suitably adapting a crosslinked structure itself of a cured article of the above composition without using any flame retardant material and without particularly highly filling an inorganic filler. The present invention provides an epoxy resin composition comprising an epoxy resin (A), a phenolic resin (B), an inorganic filler (C) and a curing accelerator (D), wherein a flexural modulus E (kgf/mm²) at 240 ± 20°C of a cured article obtained by curing the composition is a value satisfying $0.015W + 4.1 \leq E \leq 0.27W + 21.8$ in the case of $30 \leq W < 60$, or a value satisfying $0.30W - 13 \leq E \leq 3.7W - 184$ in the case of $60 \leq W \leq 95$ wherein W (wt%) is a content of the inorganic filler (C) in the cured article. The cured article of this composition forms a foamed layer during thermal decomposition or at ignition to exert flame retardancy.

[Selected Drawing] Fig. 1